

Specifications

Insulation Resistance:	10 ¹² Ω min.
Withstanding Voltage:	1,000 V _{RMS} for 1 minute
Contact Resistance:	10mΩ max. at 10mA / 20mV
Current Rating:	1A max.
Operating Temperature Range:	-55°C ~ +125°C
Acceptable Pin Diameter:	0.46 ±0.05
Mating Cycles:	100 insertions min.

Materials and Finish

Housing: PCT, 30% glass filled Polyester, UL94V-0
 Contact: Inner clip – Beryllium Copper (BeCu), Au over Ni (2-3μm)
 Outer sleeve – Machined Brass, Sn (5μm) over Ni (2-3μm)



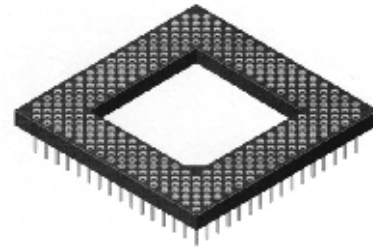
Features

- ⇨ Custom specific pin counts with grids to 41x41
- ⇨ Pin-Grid-Array precision-IC-Sockets, with displaced contacts, for picking up of ICs with high packing density.
- ⇨ Contacts with 6-finger-clip, for low insertion and withdrawal force

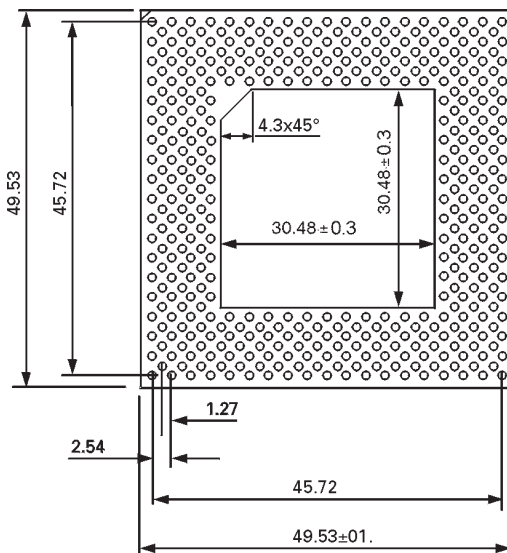
Part Number (Details)

YED210 - 321 37 - 0 B S 4

Series No.	
No. of Contact Pins	
Grid	
Design No.	
Inner Contact Plating B = Gold	
Outer Sleeve Plating S = Solder	
Terminal Style	

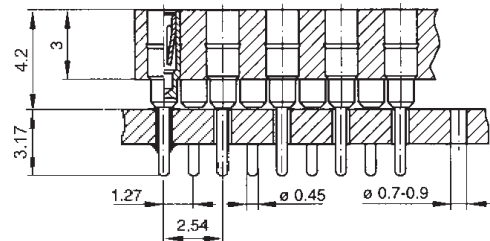


Outline Socket Dimensions (Grid 37 x 37)



Contact Position Detail

Without Stand-off pins (Standard)



With Stand-off pins

